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## CONTENTS

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## PAGE REGULAR ISSUE PAPERS

- 1859 Effect of Crystal Orientation on Mechanically Induced Sn Whiskers on Sn-Cu Plating
  Yukiko Mizuguchi, Yosuke Murakami, Shigetaka Tomiya, Tadashi Asai, Tomoya Kiga, and Katsuaki Suganuma
- Development of Sn-Ag-Cu-X Solders for Electronic Assembly by Micro-Alloying with Al Adam J. Boesenberg, Iver E. Anderson, and Joel L. Harringa
- 1882 Effect of Multiwall Carbon Nanotubes on Electrical and Structural Properties of Polyaniline M. Nagaraja, H.M. Mahesh, J. Manjanna, K. Rajanna, M.Z. Kurian, and S.V. Lokesh
- Polymer-Protected Cu-Ag Mixed NPs for Low-Temperature Bonding Application

  Jianfeng Yan, Guisheng Zou, Aiping Wu, Jialie Ren, Anming Hu, and Y. Norman Zhou
- 1893 Influence of 0.03 wt.% Carbon Black Addition on the Performance of Sn-3.5Ag Lead-Free Solder Phung Van Son, Akira Fujitsuka, and Ken-Ichi Ohshima
- Influence of Poly(ethylene glycol) Degradation on Voiding Sporadically Occurring in Solder Joints with Electroplated Cu F. Wafula, L. Yin, P. Borgesen, D. Andala, and N. Dimitrov
- 1907 Disabling of Nanoparticle Effects at Increased Temperature in Nanocomposite Solders
  Omid Mokhtari, Ali Roshanghias, Roya Ashayer, Hiren R. Kotadia, Farzad Khomamizadeh, Amir H. Kokabi, Michael P. Clode, Mark Miodownik, and Samjid H. Mannan
- 1915 Phase Equilibria and Thermodynamic Basis for the Cd-Se and Pb-Se Binary Systems
  Yajun Liu, Zhitao Kang, Guang Sheng, Lijun Zhang, Jiang Wang, and Zhaohui Long
- 1924 Improvement of Bondability by Depressing the Inhomogeneous Distribution of Nanoparticles in a Sintering Bonding Process with Silver Nanoparticles
  Jianfeng Yan, Guisheng Zou, Aiping Wu, Jialie Ren, Anming Hu, and Y. Norman Zhou
- 1931 Dislocation Reduction by Glide in Epitaxial IV-VI Layers on Si Substrates
  H. Zogg
- Demonstrating Valence Band-Edge Effective Work Function by Aluminum Implantation in High-k/Metal Gate p-MOSFET with Incorporated Fluorine

  Y.W. Chen, C.M. Lai, L.W. Cheng, C.H. Hsu, and C.W. Liang
- 1941 Growth of CdS Nanoneedles by Pulsed Laser Deposition
  Li Chen, Xiaoniu Fu, Jushui Lai, Jian Sun, Zhifeng Ying, Jiada Wu, and Ning Xu
- Influence of Substrate Temperature on Structural Properties and Deposition Rate of AlN Thin Film Deposited by Reactive Magnetron Sputtering

  Hao Jin, Bin Feng, Shurong Dong, Changjian Zhou, Jian Zhou, Yi Yang, Tianling Ren, Jikui Luo, and Demiao Wang
- 1955 Unusual Rectifying Response of Nanojunctions Using Randomly Oriented Nanorods (RON) of ZnO Irradiated with 80-MeV Oxygen Ions
  Sayan Bayan and Dambarudhar Mohanta
- 1962 RF Power Effect on the Properties of Sputtered ZnO Films for Channel Layer Applications in Thin-Film Transistors

  M.I. Medina-Montes, H. Arizpe-Chávez, L.A. Baldenegro-Pérez, M.A. Quevedo-López, and R. Ramírez-Bon
- 1970 Influence of Dopants on Electrical Properties of ZnO-V<sub>2</sub>O<sub>5</sub> Varistors Deduced from AC Impedance and Variable-Temperature Dielectric Spectroscopy
  Jun Wu, Taotao Li, Ting Qi, Qingwei Qin, Guangqiang Li, Bailin Zhu, Run Wu, and Changsheng Xie
- 1978 Half-Metallic Ferromagnetism in the Ti<sub>2</sub>CoGe Heusler Compound Selçuk Kervan and Nazmiye Kervan

1982	Electron-Beam Sensitivity and Patterning of an Aqueous-Develop, Epoxy-Based Polynorbornene Dielectric Material Mehrsa Raeis-Zadeh and Paul A. Kohl
1990	New Method for Evaluating the Peltier Coefficient Based on Temperature Measurements in a Thermoelectric Module J. Garrido and A. Casanovas
1996	Fabrication of Transparent BaNaB <sub>9</sub> O <sub>15</sub> Glass–Microcrystal Composites  Rahul Vaish and K.B.R. Varma
2001	Mechanical Properties of Anisotropic Conductive Adhesive Film Under Hygrothermal Aging and Thermal Cycling Li-Lan Gao, Xu Chen, and Hong Gao
2010	Long-Term Stability of Mold Compounds and the Influence on Semiconductor Device Reliability  Joachim Mahler and Manfred Mengel
2018	Shear Strength and Failure Modes of As-Bonded Gold and Copper Ball Bonds on Aluminum Metallization

C.D. Breach and T.K. Lee